



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-09-15
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ITA25B1RL	HDO7*TAW025B	A	SHENZHEN B/E	2016-09-15
Amount		UoM	Unit type	ST ECOPACK Grade
80.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	NiPdAuAg	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	4.9-6-1.75	8	GULL WING	
Comment	SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HDO7*TAW025B					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other Inorganic materials	3.411	mg	supplier	die	Silicon (Si)	7440-21-3		3.322	mg	973908	41525
				supplier	metallization	Aluminium (Al)	7429-90-5		0.024	mg	7036	300
				supplier	Passivation	Silicon Oxide	7631-86-9		0.016	mg	4691	200
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.016	mg	4691	200
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	586	25
				supplier	back side metallization	Gold (Au)	7440-57-5		0.006	mg	1759	75
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.025	mg	7329	313
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.025	mg	7329	313
Leadframe	Copper & its alloys	29.796	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.710	mg	997114	371375
				supplier	alloy	Iron (Fe)	7439-89-6		0.014	mg	470	175
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.025	mg	837	313
				supplier	metallization	Nickel (Ni)	7440-02-0		0.044	mg	1477	550
				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	34	13
				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	34	13
				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	34	13
				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	34	13
Die attach	Other Organic Materials	1.356	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		1.234	mg	910029	15421
				supplier	glue or tape	acrylate	Proprietary		0.068	mg	50148	850
				supplier	glue or tape	Methacrylate	Proprietary		0.054	mg	39823	675
Bonding wires	Other Inorganic materials	0.196	mg	supplier	wire	Copper (Cu)	7440-50-8		0.196	mg	1000000	2450
Encapsulation	Other Organic Materials	45.241	mg	supplier	mold compound	Silica, vitreous	60676-86-0		39.179	mg	866006	489738
				supplier	mold compound	Epoxy Resin	25068-38-6		3.393	mg	74998	42413
				supplier	mold compound	Phenol Resin	29690-82-2		2.262	mg	49999	28275
				supplier	mold compound	Carbon black	1333-86-4		0.226	mg	4995	2825
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.181	mg	4002	2263